



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2018-09-03
<b>Company Unique ID</b>	NL 008751171B01		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	Giovanni Giapello	<b>Representative Title</b>	ADG MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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Legal Statement		
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>
		Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPSC12065G2Y-TR	BT(9*4L01AT7	A	3068	2018-09-03
Amount	UoM	Unit type	ST ECOPACK Grade	
1380.00	mg	Each	ECOPACK2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	245	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10.2-7.2-4.5	3	GULL WING	
Comment	H2PAK HC 2-3 Leads			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015			
Query			Response
1 - Product(s) meets EU RoHS requirement without any exemptions			FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)			FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)			TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions			FALSE
Exemption Id.	Description		
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)		

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017			
Query			Response
1 - Product(s) meets EU ELV requirements without any exemptions			FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)			TRUE
Exemption Id.	Description		
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)		

QueryList : California Prop65 list, dated 25th May 2018			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.25	Die - Leadframe	183
Lead	2.44	Soft solder	1767

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	2.439		1767
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	2.439		954973

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	BT9*4L01A7					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	2.442	mg	supplier	die	Silicium carbide	409-21-2		2.311	mg	946355	1675
				supplier	metallization	Aluminium (Al)	7429-90-5		0.026	mg	10647	19
				supplier	metallization	Gold (Au)	7440-57-5		0.004	mg	1637	3
				supplier	metallization	Nickel (Ni)	7440-02-0		0.021	mg	8600	15
				supplier	metallization	Silver (Ag)	7440-22-4		0.044	mg	18018	32
				supplier	metallization	Titanium (Ti)	7440-32-6		0.002	mg	819	1
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	410	1
				supplier	back side metallization	Gold (Au)	7440-57-5		0.004	mg	1638	3
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.018	mg	7371	13
				supplier	polymer die coating	PXI1 Gamma-butyrolactone	96-48-0		0.011	mg	4505	8
				supplier	alloy	Copper (Cu)	7440-50-8		846.677	mg	998428	613534
				Leadframe	M-004 Copper and its alloys	848.010	mg	supplier	alloy	Iron (Fe)	7439-89-6	
supplier	alloy	Iron Phosphide (FeP)	26508-33-8						0.254	mg	300	184
supplier	metallization	Nickel (Ni)	7440-02-0						0.214	mg	252	155
supplier	metallization	Phosphorus (P)	7723-14-0						0.017	mg	20	12
supplier	solder	Lead (Pb)	7439-92-1					7a-Lead in high mel	2.439	mg	954973	1767
Soft solder	Solder	2.554	mg	supplier	solder	Silver (Ag)	7440-22-4		0.064	mg	25059	46
				supplier	solder	Tin (Sn)	7440-31-5		0.051	mg	19968	37
				supplier	wire	Aluminium (Al)	7429-90-5		1.385	mg	1000000	1004
Encapsulation	M-011 Other inorganic materials	521.875	mg	supplier	mold compound	Silica, vitreous	60676-86-0		456.641	mg	875001	330899
				supplier	mold compound	Tetramethyl-biphenyl-diy1-bis oxymethylene-bi	EC 413-900-7		20.875	mg	40000	15127
				supplier	mold compound	Epoxy Resin	25068-38-6		15.656	mg	30000	11345
				supplier	mold compound	phenol resin	29690-82-2		26.094	mg	50000	18909
				supplier	mold compound	Carbon black	1333-86-4		2.609	mg	4999	1891
connections coating	Solder	3.734	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		3.734	mg	1000000	2706